

AMENDMENTS TO THE CLAIMS

1. (Original) An electromagnetic wave shielding material which comprises a transparent substrate and a fine line pattern formed thereon,

wherein the fine line pattern comprises a metal plating film using a physically developed metal silver as a catalytic nucleus.

2. (Original) The electromagnetic wave shielding material according to Claim 1, wherein the fine line pattern has a thickness of 15 μm or less and a line width of 40 μm or less, a total luminous transmittance of 50% or higher, and a surface resistance of 10 ohm/\square or less.

3. (Currently Amended) The electromagnetic wave shielding material according to Claim ~~1 or 2~~, wherein the total luminous transmittance is 60% or higher.

4. (Currently Amended) The electromagnetic wave shielding material according to ~~any one of Claims 1 to 3~~ 2, wherein the surface resistance is 7 ohm/\square or less.

5. (Currently Amended) The electromagnetic wave shielding material according to ~~any one of Claims 1 to 4~~ 2, wherein the thickness of the fine line pattern is 0.5 to 15 μm .

6. (Currently Amended) The electromagnetic wave shielding material according to ~~any one of Claims 1 to 5~~, wherein the thickness of the fine line pattern is 2 to 12 μm .

7. (Currently Amended) The electromagnetic wave shielding material according to ~~any one of Claims 1 to 6~~ 2, wherein the line width of the fine line pattern is 1 to 40 μm .

8. (Currently Amended) The electromagnetic wave shielding material according to ~~any one of Claims 1 to 7~~, wherein the plating is an electrolytic plating.

9. (Currently Amended) The electromagnetic wave shielding material according to Claim ~~8~~ 1, wherein the plating is at least one kind of plating selected from copper and nickel.

10. (Original) A process for preparing an electromagnetic wave shielding material which comprises exposing a light-sensitive material having a physical development nuclei layer and a silver halide emulsion layer on a transparent substrate in this order, precipitating metal silver with an optional fine line pattern onto the physical development nuclei layer by physical development, then, removing a layer provided on the physical development nuclei layer, and subjecting to plating a metal with the use of the physically developed metal silver as a catalytic nucleus.

11. (Original) The process for preparing an electromagnetic wave shielding material according to Claim 10, wherein the fine line pattern has a thickness of 15 μm or less and a line width of 40 μm or less, a total luminous transmittance of 50% or higher, and a surface resistance of 10 ohm/\square or less.

12. (Currently Amended) The process for preparing an electromagnetic wave shielding material according to Claim ~~10 or~~ 11, wherein the total luminous transmittance is 60% or higher.

13. (Currently Amended) The process for preparing an electromagnetic wave shielding material according to ~~any one of Claims 10 to 12~~ 11, wherein the surface resistance is 7 ohm/□ or less.

14. (Currently Amended) The process for preparing an electromagnetic wave shielding material according to ~~any one of Claims 10 to 13~~ 11, wherein the thickness of the fine line pattern is 0.5 to 15 μm.

15. (Currently Amended) The process for preparing an electromagnetic wave shielding material according to ~~any one of Claims 10 to 14~~, wherein the thickness of the fine line pattern is 2 to 12 μm.

16. (Currently Amended) The process for preparing an electromagnetic wave shielding material according to ~~any one of Claims 10 to 15~~ 11, wherein the line width of the fine line pattern is 1 to 40 μm.

17. (Currently Amended) The process for preparing an electromagnetic wave shielding material according to ~~any one of Claims 10 to 16~~, wherein the plating is an electrolytic plating.

18. (Currently Amended) The process for preparing an electromagnetic wave shielding material according to Claim ~~17~~ 10, wherein the plating is at least one kind of plating selected from copper and nickel.

19. (Currently Amended) The process for preparing an electromagnetic wave shielding material according to ~~any one of Claims 10 to 16~~ 18, wherein an electrolytic plating is carried out by dipping a transparent substrate on which a physically developed silver has been formed in a bath containing copper sulfate and sulfuric acid as main components with a current density of 1 to 20 ampere/dm² at 10 to 40°C.